

# BB179LX

## UHF variable capacitance diode

Rev. 01 — 13 April 2006

Preliminary data sheet

## 1. Product profile

### 1.1 General description

The BB179LX is a planar technology variable capacitance diode in a SOD882T ultra small leadless plastic SMD package. The excellent matching performance is achieved by gliding matching and a Direct Matching Assembly (DMA) procedure.

### 1.2 Features

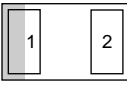

- Excellent linearity
- Excellent matching to 2 % DMA
- Ultra small leadless SMD package
- $C_{d(28V)}$ : 2.1 pF;  $C_{d(1V)}$  to  $C_{d(28V)}$  ratio typical 9
- Low series resistance

### 1.3 Applications

- Voltage Controlled Oscillators (VCO)
- Electronic tuning in VHF television tuners

## 2. Pinning information

Table 1. Discrete pinning

| Pin | Description | Simplified outline  | Symbol  |
|-----|-------------|---|---|
| 1   | cathode     |  <p>Transparent top view</p> |  <p>sym008</p> |
| 2   | anode       |   |   |

[1] The marking bar indicates the cathode.

## 3. Ordering information

Table 2. Ordering information

| Type number | Package |  |         |
|-------------|---------|--|---------|
|             | Name    | Description  | Version |
| BB179LX     | -       | leadless ultra small plastic package; 2 terminals; body 1.0 × 0.6 × 0.4 mm | SOD882T |

**PHILIPS**

## 4. Marking

**Table 3. Marking**

| Type number | Marking code |
|-------------|--------------|
| BB179LX     | L4           |

## 5. Limiting values

**Table 4. Limiting values**

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

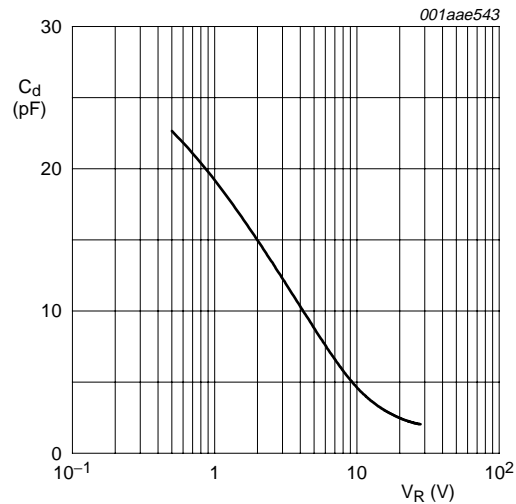
| Symbol    | Parameter            | Conditions | Min | Max  | Unit |
|-----------|----------------------|------------|-----|------|------|
| $V_R$     | reverse voltage      |            | -   | 30   | V    |
| $I_F$     | forward current      |            | -   | 20   | mA   |
| $T_{stg}$ | storage temperature  |            | -55 | +150 | °C   |
| $T_j$     | junction temperature |            | -55 | +125 | °C   |

## 6. Characteristics

**Table 5. Characteristics**

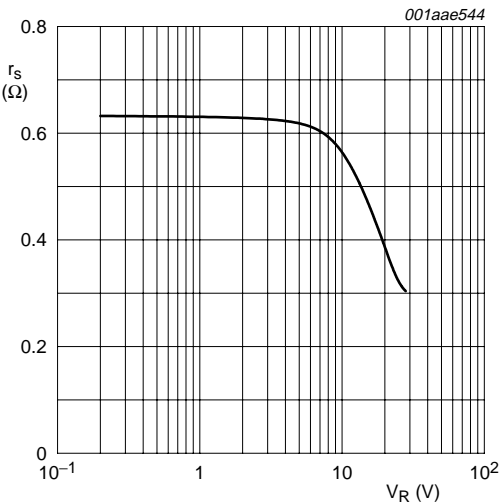
$T_j = 25\text{ °C}$  unless otherwise specified.

| Symbol                          | Parameter                  | Conditions   | Min  | Typ  | Max  | Unit     |
|---------------------------------|----------------------------|--|------|------|------|----------|
| $I_R$                           | reverse current            | see <a href="#">Figure 3</a>   |      |      |      |          |
|                                 |                            | $V_R = 30\text{ V}$  | -    | -    | 10   | nA       |
|                                 |                            | $V_R = 30\text{ V}; T_j = 85\text{ °C}$  | -    | -    | 200  | nA       |
| $r_s$                           | diode series resistance    | $f = 470\text{ MHz}; C_d = 30\text{ pF}$ ; see <a href="#">Figure 2</a>          | -    | 0.65 | -    | $\Omega$ |
| $C_d$                           | diode capacitance          | see <a href="#">Figure 1</a> and <a href="#">Figure 4</a> ; $f = 1\text{ MHz}$ ; |      |      |      |          |
|                                 |                            | $V_R = 1\text{ V}$   | 18.2 | -    | 21.3 | pF       |
|                                 |                            | $V_R = 28\text{ V}$  | 1.95 | 2.1  | 2.22 | pF       |
| $\frac{C_{d(1V)}}{C_{d(2V)}}$   | diode capacitance ratio    | $f = 1\text{ MHz}$   | -    | 1.27 | -    |          |
| $\frac{C_{d(1V)}}{C_{d(28V)}}$  | diode capacitance ratio    | $f = 1\text{ MHz}$   | 8.45 | 9    | 10.9 |          |
| $\frac{C_{d(25V)}}{C_{d(28V)}}$ | diode capacitance ratio    | $f = 1\text{ MHz}$   | -    | 1.05 | -    |          |
| $\frac{\Delta C_d}{C_d}$        | diode capacitance matching | $V_R = 1\text{ V to } 28\text{ V}$ ; in sequence of 5 diodes (gliding)           | -    | -    | 2    | %        |



$f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ\text{C}.$

Fig 1. Diode capacitance as a function of reverse voltage; typical values



$f = 470 \text{ MHz}; T_j = 25 \text{ }^\circ\text{C}.$

Fig 2. Diode serial resistance as a function of reverse voltage; typical values

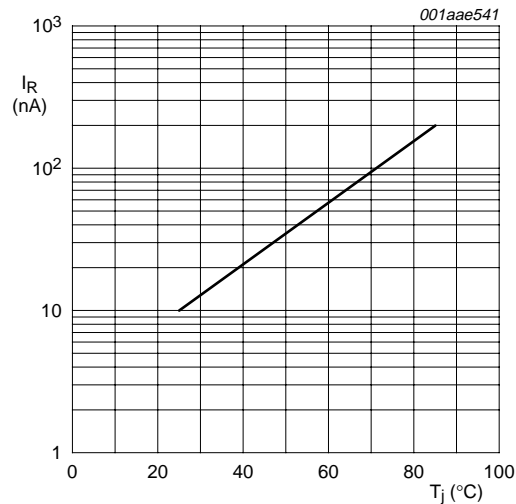
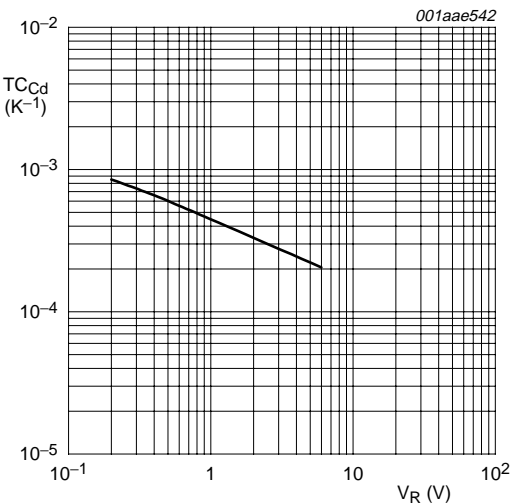


Fig 3. Reverse current as function of junction temperature; maximum values



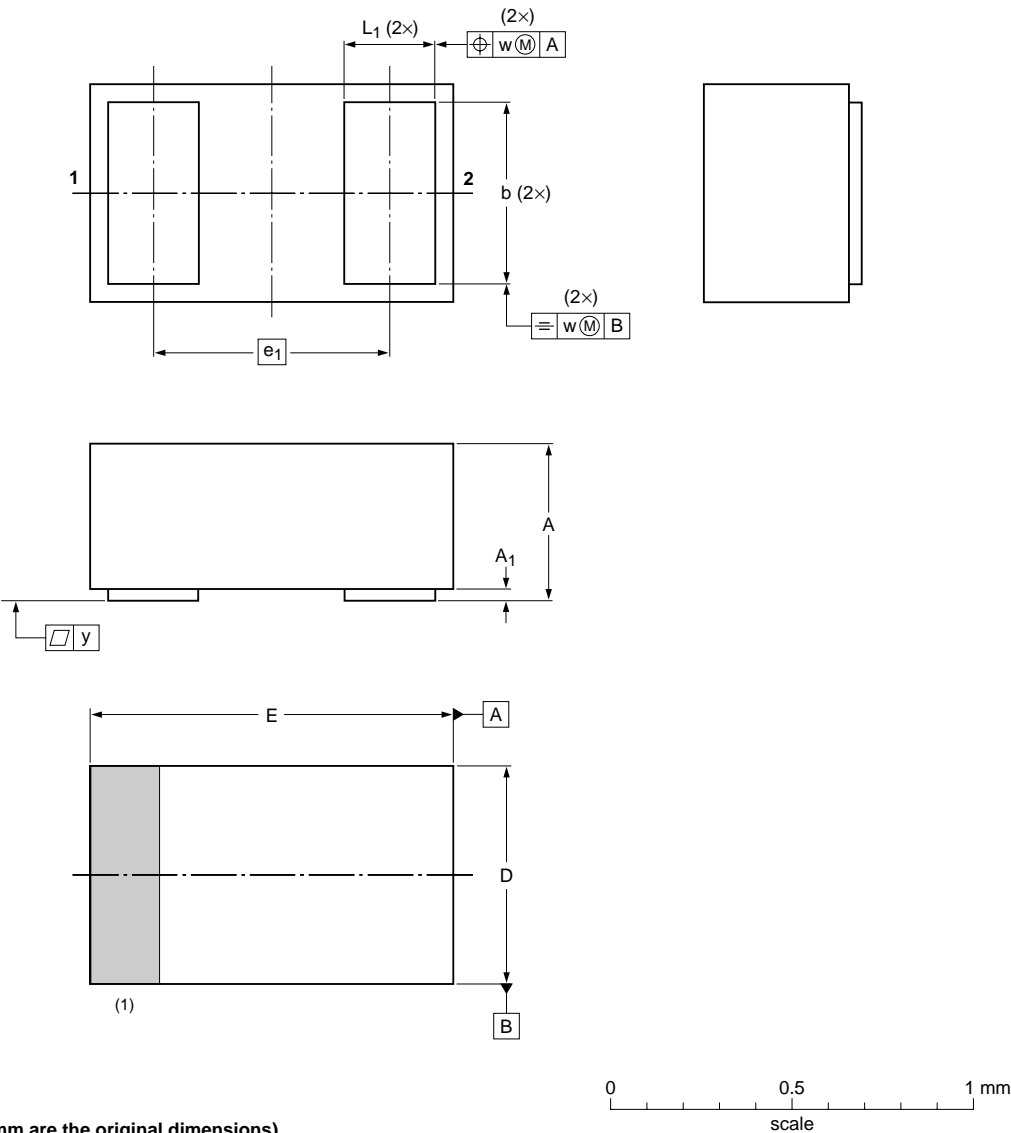
$T_j = 25 \text{ }^\circ\text{C} \text{ to } 85 \text{ }^\circ\text{C}.$

Fig 4. Temperature coefficient of diode capacitance as a function of reverse voltage; typical values

7. Package outline

Leadless ultra small plastic package; 2 terminals; body 1 x 0.6 x 0.4 mm

SOD882T



DIMENSIONS (mm are the original dimensions)

| UNIT | A            | A <sub>1</sub> max | b            | D            | E            | e <sub>1</sub> | L <sub>1</sub> | w   | y    |
|------|--------------|--------------------|--------------|--------------|--------------|----------------|----------------|-----|------|
| mm   | 0.40<br>0.36 | 0.04               | 0.55<br>0.45 | 0.65<br>0.55 | 1.05<br>0.95 | 0.65           | 0.30<br>0.22   | 0.1 | 0.03 |

Note

1. The marking bar indicates the cathode

| OUTLINE<br>VERSION | REFERENCES |       |       |  | EUROPEAN<br>PROJECTION | ISSUE DATE           |
|--------------------|------------|-------|-------|--|------------------------|----------------------|
|                    | IEC        | JEDEC | JEITA |  |                        |                      |
| SOD882T            |            |       |       |  |                        | 04-12-14<br>06-04-12 |

Fig 5. Package outline SOD882T

8. Revision history

Table 6. Revision history

| Document ID | Release date | Data sheet status      | Change notice | Supersedes |
|-------------|--------------|------------------------|---------------|------------|
| BB179LX_1   | 20060413     | Preliminary data sheet | -             | -          |

## 9. Legal information

### 9.1 Data sheet status

| Document status <sup>[1][2]</sup> | Product status <sup>[3]</sup> | Definition  |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet      | Development                   | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet    | Qualification                 | This document contains data from the preliminary specification.                       |
| Product [short] data sheet        | Production                    | This document contains the product specification.                                     |

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[2] The term 'short data sheet' is explained in section "Definitions".

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